

# PATENT ABSTRACTS OF JAPAN

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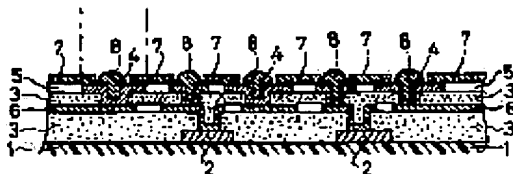
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## (54) MULTI-LAYER PRINTED CIRCUIT BOARD

### (57)Abstract:

**PROBLEM TO BE SOLVED:** To make a signal line shielded surely by a ground layer from electromagnetic waves, by separating a mounted pad connected to the signal layer into a plurality of sections by a pattern layer that includes a mounting pad connected to the ground layer.

**SOLUTION:** A ground layer 6 and a signal layer 2 are laminated with an insulating layer in between on a board 1. A mounting pad connected to a ground layer 6 and a mounting pad connected to the signal layer 2 are formed on the face of laminated layer. In this case, the mounting pad is connected through a via hole 4 to the ground layer, and at the same time a soldered body is preferably formed at the mounting pad that is located at the via hole 4. The other mounting pad is connected to the signal layer 2 through the via hole 4, and a soldered body is preferably formed at the mounting pad located at the via hole 4.



## LEGAL STATUS

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